REMARKS

Applicants have amended claims 1 and 5.

Claims 1-8 have been rejected under 35 USC 102(a) as anticipated by U.S. Patent Application Publication No. 2002/0047210 (Yamada). Applicants respectfully traverse this rejection.

Original claim 1 recites a supporting body disposed on the front surface and having an opening to expose at least part of the second wiring. The Examiner equates Yamada's insulating layer 210 to the claimed supporting body. Applicants respectfully disagree with the Examiner because Yamada's insulating layer 210 is not bonded, as stated in original claim 1, to the front surface of Yamada's semiconductor chip 11, 12 and 13 as claimed.

Applicants have amended claim 1 to recite an adhesive layer bonding the supporting body to the front surface so that the Examiner understands that the claimed supporting body is bonded to the front surface of the semiconductor chip. This amendment finds support, for example, at page 3, lines 24-29, of the specification. No portion of Yamada teaches or suggests the claimed adhesive layer that bonds the supporting body to the front surface of the semiconductor chip.

Claim 5 as amended recites substantially the same adhesive layer as claim 1. Thus, the rejection of claims 1-8 under 35 USC 102(a) on Yamada should be withdrawn because Yamada does not teach or suggest the claimed adhesive layer.

In light of the above, a Notice of Allowance is solicited.

In the event that the transmittal letter is separated from this document and the Patent and Trademark Office determines that an extension and/or other relief is required, applicants petition

for any required relief including extensions of time and authorize the Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to Deposit Account No. 03-1952, referencing Docket No. 492322017700.

Respectfully submitted,

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